



IFW /

Docket: 8028-42 (SPX200304-0017US)

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Hyun-Woo Kim et al.

Examiner: Amanda C. Walke

Serial No: 10/787,368

Group Art Unit: 1752

Filed: February 26, 2004

For: **METHOD OF FORMING AN UNDERLAYER OF A BI-LAYER RESIST FILM AND METHOD OF FABRICATING A SEMICONDUCTOR DEVICE USING THE SAME**

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**AMENDMENT**

Sir:

In response to the Office Action dated June 29, 2005, please amend the application as set forth herein:

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**CERTIFICATE OF MAILING 37 C.F.R. §1.8(a)**

I hereby certify that this correspondence (and any document referred to as being attached or enclosed) is being deposited with the United States Postal Service as first class mail, postage paid in an envelope addressed to: Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450, on September 29, 2005.

Dated: September 29, 2005

  
Scott L. Appelbaum